L Number	Hits	Search Text	DB	Time stamp
1 Number	2	("6348725").PN.	USPAT;	2003/07/18 10:36
*		( 0340723 ).FM.	US-PGPUB;	2003,07,10 10.30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	1671	mem with switch	USPAT.;	2003/07/18 10:37
			US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	174	mem with switch and etch\$3 and intermediate	USPAT;	2003/07/18 10:39
		•	US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
			IBM_TDB	
4	0	mem with switch and etch\$3 and intermediate	USPAT;	2003/07/18 10:40
		and Tialn	US-PGPUB;	
	•		EPO; JPO;	
		•	DERWENT;	-
_	1.54	in a sum of the sum of mindu	IBM_TDB	2002/07/10 10 41
5	174	intermediate and Tialn	USPAT;	2003/07/18 10:41
		·	US-PGPUB; EPO; JPO;	
			DERWENT;	
	ļ.		IBM TDB	
6	. 29	intermediate near33 Tialn	USPAT;	2003/07/18 12:19
"		intermediate nearby rearri	US-PGPUB;	2003/01/10 12:13
			EPO; JPO;	
¥			DERWENT;	
			IBM_TDB	
7	0	sun.in. and li.in. and redeker.in	USPAT;	2003/07/18 12:19
,			US-PGPUB;	,
			EPO; JPO;	
-		,	DERWENT;	
			IBM_TDB	
8	14497	sun.in. li.in. and redeker.in	USPAT;	2003/07/18 12:20
	!		US-PGPUB;	1
			EPO; JPO; DERWENT;	
			IBM TDB	
9	682	sun.in. and li.in. redeker.in	USPAT;	2003/07/18 12:20
		1	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
10	52813	sun.in. li.in. redeker.in	USPAT;	2003/07/18 12:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB .	0000/65/55
11	25	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:21
	1	CMP and amine	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
12	100	(sun.in. li.in. redeker.in) and CU and	IBM_TDB	2002/07/10 12:21
12	103	(sun.in. li.in. redeker.in) and CU and CMP	USPAT; US-PGPUB;	2003/07/18 12:21
		G. I.E.	EPO; JPO;	
			DERWENT;	
·		·	IBM TDB	
13	93	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:21
		CMP and polish\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	25	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:22
		CMP and polish\$3 and amine	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

15	63	(sun.in. li.in. redeker.in) and CU and CMP and polish\$3 and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/18 12:22
			IBM TDB	
16	431105	(sun.in. li.in. redeker.in) and CU and CMP and polish\$3 and pad adn amine	USPAT; US-PGPUB;	2003/07/18 12:22
		CAP and portants and pad adm amine	EPO; JPO; DERWENT;	
			IBM_TDB	
17	254533		USPAT;	2003/07/18 12:22
		CMP and polish\$3 and pad adn amine and	US-PGPUB;	
		organic	EPO; JPO; DERWENT;	
			IBM TDB	·
18	12132	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:23
10	12132	CMP and polish\$3 and pad adn amine and	US-PGPUB;	2003/07/18 12:23
		organic and wafer	EPO; JPO;	
· ·		organizo ana mazor	DERWENT;	
			IBM TDB	
19	13	(sun.in. li.in. redeker.in) and CU and	USPAT;	2003/07/18 12:23
		CMP and polish\$3 and pad and amine and	US-PGPUB;	
İ		organic and wafer	EPO; JPO;	İ
		·	DERWENT;	
			IBM_TDB	
-	0	"cu cmp polishing pad cleaning".ti.	USPAT;	2002/07/23 07:10
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
	1	"cu cmp polishing".ti.	IBM_TDB	2002/06/08 18:28
-	1	"cu cmp porishing".tr.	USPAT; US-PGPUB;	2002/06/08 18:28
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
-	0	cu near3 cmp near3 polishing near3 pad near3	USPĀT;	2002/08/05 14:02
		cleaning	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	5	sun.in. & li.in. & redeker.in.	USPAT;	2002/06/08 18:35
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	"REMOVING TONER FROM PRINTED MATERIAL".ti.	USPAT;	2002/06/08 18:35
			US-PGPUB;	1002,00,00 20100
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	,
-	0	"REMOVING TONER FROM PRINTED MATERIAL"	USPAT;	2002/06/08 18:35
			US-PGPUB;	
			EPO; JPO;	• .
			DERWENT;	
_	28881	(amine amide) and ("ph 5" "ph 6" "ph 7" "ph	<pre>IBM_TDB USPAT;</pre>	2002/07/23 07:43
	20001	8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12")	US-PGPUB;	2002/01/23 01:43
		and organic and (acid base)	EPO; JPO;	
			DERWENT;	
		•	IBM TDB	
-	4278	((amine amide) and ("ph 5" "ph 6" "ph 7" "ph	USPAT;	2002/07/23 07:19
		8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12")	US-PGPUB;	,
		and organic and (acid base)) and	EPO; JPO;	
	1	ethylenediamine and (phosphoric acetic	DERWENT;	
		sulfuric potassium sodium ammonium) near5	IBM_TDB	
		(acid hydroxide) and ( DI dionized water)		

			,	7
-	10	(((amine amide) and ("ph 5" "ph 6" "ph 7"	USPAT;	2002/07/23 07:21
ľ		"ph 8" "ph 9" "ph 9" "ph 10" "ph 11" "ph	US-PGPUB;	
		12") and organic and (acid base)) and	EPO; JPO;	
		ethylenediamine and (phosphoric acetic	DERWENT;	
		sulfuric potassium sodium ammonium) near5	IBM_TDB	
1		(acid hydroxide) and (DI dionized water))		
		and (copper cu) and (cmp "chemical mechanical polishing")		
_	12		USPAT;	2002/07/23 07:48
}	12	8" "ph 9" "ph 9" "ph 10" "ph 11" "ph 12")	US-PGPUB;	2002/07/25 07:40
		and organic and (acid base) and (cmp	EPO; JPO;	
		"chemical mechaical") and rins\$4 and clean\$4	DERWENT;	
		and wafer	IBM_TDB	
-	11	"163582"	USPAT;	2002/07/23 07:49
			US-PGPUB;	
1			EPO; JPO;	`
			DERWENT; .	
			IBM_TDB	
-	5	"359141"	USPAT;	2002/07/23 07:51
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	F-4	114635311	IBM_TDB	2002/07/22 07 52
-	53	"46353"	USPAT; US-PGPUB;	2002/07/23 07:53
}			EPO; JPO;	
			DERWENT;	
			IBM TDB	·
_	0	"99/46353"	USPAT;	2002/07/23 07:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	99/46353	USPAT;	2002/07/23 07:53
	1		US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	
	0	(copper cu) near3 cmp near3 polishing near3	IBM_TDB USPAT;	2002/08/05 14:22
-	<u>ن</u>	pad near3 clean\$3	US-PGPUB;	2002/08/05 14:22
		pad hears creanss	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1638	small.in.	USPAT;	2002/08/05 14:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/00/07
-	60	small.in. and clean	USPAT;	2002/08/05 14:26
			US-PGPUB;	
		·	EPO; JPO; DERWENT;	
		•	IBM TDB	.
-	8	small.in. and clean and pad	USPAT;	2002/08/05 14:26
	1		US-PGPUB;	
.			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
-	21	small.in. and clean\$4 and pad	USPAT;	2002/08/05 14:33
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		and and analythou and make a	IBM_TDB	0000/00/05
-	478	cmp and polish\$4 and method and second\$4 and	USPAT;	2002/08/05 14:42
		clean\$4 and pad and (cu copper) and solution	US-PGPUB;	
	-		EPO; JPO; DERWENT;	
			IBM_TDB	
	L			

-	90		USPAT;	2002/08/05 14:44
		clean\$4 and pad and (cu copper) and solution	US-PGPUB;	
		and amin\$4	EPO; JPO;	·
•			DERWENT;	
			IBM_TDB	
-	8	small.in. and clean and pad	USPAT;	2002/08/05 16:05
			US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
-	21328		USPAT;	2002/08/05 16:23
		acetic	US-PGPUB;	
			EPO; JPO;	
· ·		·	DERWENT;	
			IBM_TDB	
-	2	The state of the s	USPAT;	2002/08/05 16:05
		acetic	US-PGPUB;	
		,	EPO; JPO;	
·			DERWENT;	
}			IBM_TDB	
-	2458	1 2 - 1 2 - 1 - 1	USPAT;	2002/08/05 16:26
		acetic and method and wafer and surface	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	3216	(diw water) and cmp and clean\$4 and pad	USPAT;	2002/08/05 16:27
	,	(amine \$6amine) and method and wafer and	US-PGPUB;	
	1	surface and organic and (cu copper)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3216		USPAT;	2002/08/05 16:28
		(amine \$6amine) and method and wafer and	US-PGPUB;	
		surface and organic and (cu copper) and	EPO; JPO;	
	1	((diw water) and cmp and clean\$4 and pad	DERWENT;	
		(amine \$6amine) and method and wafer and	IBM_TDB	
		surface and organic and (cu copper))		
-	1072		USPAT;	2002/08/05 16:29
		(amine) and method and wafer and surface and	US-PGPUB;	
		organic and (cu copper) and ((diw water) and	EPO; JPO;	
		cmp and clean\$4 and pad (amine \$6amine) and	DERWENT;	
		method and wafer and surface and organic and	IBM_TDB	•
		(cu copper)) and clean\$4 near5 pad		( (
-	11	, the same and the same and the same party and	USPAT;	2002/08/05 16:41
		amine and method and wafer and surface and	US-PGPUB;	
		organic and (cu copper) and ((diw water) and	EPO; JPO;	
		cmp and clean\$4 and pad (amine \$6amine)and method and wafer and surface and organic and	DERWENT;	
		(cu copper)) and clean\$4 near5 pad	IBM_TDB	,
	2	("5,616,069").PN.	USPAT;	2002/08/05 16:39
		( 5,5±0,005 ,.1M.	US-PGPUB;	2002/00/05 10:39
			EPO; JPO;	·
		· ·	DERWENT;	
	1		IBM TDB	
-	11	(diw water) and cmp and amine and method and	USPAT;	2002/08/05 16:42
		wafer and surface and organic and (cu	US-PGPUB;	
		copper) and clean\$4 near5 pad	EPO; JPO;	
		**	DERWENT;	
			IBM TDB	
-	11	(diw water) and cmp and (hydroxylamine	USPAT;	2002/08/06 06:32
		amine) and method and wafer and surface and	US-PGPUB;	
		organic and (cu copper) and clean\$4 near5	EPO; JPO;	
		pad	DERWENT;	
-		<del>-</del>	IBM TDB	
-	40	(diw water "DI water") and cmp and method	USPAT;	2002/08/06 06:55
	i	and wafer and surface and RPM and (rate	US-PGPUB;	,
		ml/min delivery) and rins\$4 and (condition	EPO; JPO;	
		clean\$4) near5 pad	DERWENT;	
L	L		IBM_TDB	

	11	(diw water "DI water") and cmp and method	USPAT;	2002/08/06 06:57
		and wafer and surface and RPM and (rate	US-PGPUB;	9
		ml/min delivery) and rins\$4 and (condition	EPO; JPO;	
		clean\$4) near5 pad and ml/min	DERWENT;	
	111	/div unter UDT contently and own and mathed	IBM_TDB USPAT;	2002/08/08 06:36
_	"	(diw water "DI water") and cmp and method and wafer and surface and RPM and (rate	US-PGPUB;	2002/08/08 06:36
		ml/min delivery) and rins\$4 and (condition	EPO; JPO;	
-		clean\$4) near5 pad and (ml/min ml/min)	DERWENT;	
		creative, hears pad and (mr/mri mr/mri)	IBM TDB	
_	0	placing near5 polished near5 semiconductor	USPAT;	2002/08/08 06:37
		near5 substrate near5 scrubber and li.in.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	
_	0	placing near5 polished near5 semiconductor	USPAT;	2002/08/08 06:38
		near5 substrate near5 scrubber	US-PGPUB;	•
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	19821		USPAT;	2002/08/08 06:39
		and substrate	US-PGPUB;	
		·	EPO; JPO;	
	<b> </b> .		DERWENT;	
			IBM_TDB	
_	0	rincoln and delarios.in. and semiconductor	USPAT;	2002/08/08 06:39
	1	and clean and substrate	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	8	delarios.in. and semiconductor and clean and	USPAT;	2002/08/08 07:44
	8	substrate	US-PGPUB;	2002/08/08 07:44
	İ	Substitute	EPO; JPO;	
	1		DERWENT;	
		·	IBM TDB	·
_	2	"6352595"	USPAT;	2002/08/08 08:16
			US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("6,280,299").PN.	USPAT;	2002/08/08 08:17
			US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
		("4	IBM_TDB	
_	2	("6,220,941").PN.	USPAT;	2002/08/08 08:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	7
_	2	("6242079").PN.	IBM_TDB   USPAT;	2002/08/08 13:58
	1	( QZ-120/3 ) . F.N.	US-PGPUB;	2002/00/00 13:58
			EPO; JPO;	,
			DERWENT;	
		*	IBM TDB	
_	0	(""aspect ratio" and copper and etch and	USPAT;	2002/08/08 13:59
		adhesion and promotion").PN.	US-PGPUB;	,,
		• • • • • • • • • • • • • • • • • • • •	EPO; JPO;	. [
			DERWENT;	,
			IBM_TDB	
-	18	The state of the s	USPAT;	2002/08/08 14:00
		adhesion and promotion .	US-PGPUB;	
		*	EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM_TDB	
- '	17	,P	USPAT;	2002/08/08 14:00
		adhesion and promotion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

### adhesion and promotion and immersion ####################################					
IMM TIDE   Control ("4984142") or ("4909563") or ("4541945")   USPAT;	-	6	"aspect ratio" and copper and etch and adhesion and promotion and immersion	EPO; JPO;	2002/08/08 14:01
48					
or ("\$645882") or ("\$66789") or ("\$509970") or ("\$876508") or ("\$4905631") or ("\$4905631") or ("\$633993") or ("\$4905631") or ("\$518454") or ("\$4905631") or ("\$525014") or ("\$340170") or ("\$574017") or ("\$525014") or ("\$340170") or ("\$574017") or ("\$525014") or ("\$340170") or ("\$5774017") or ("\$525014") or ("\$6033993") or ("\$670226") or ("\$587608") o	-	48		USPAT;	2002/08/15 07:23
or ("4954142") or ("5084071") or ("5225034") or ("5540502") or ("5465627") or ("55662769") or ("5509970") or ("5365080") or ("5875089") or ("5875089") or ("5809970") or ("6389733") or ("6309260")).PN.  17 ("7389733") or ("4090563") or ("459145") or ("5340370") or ("5365081") or ("631943") or ("545628") or ("564562") or ("56456	•		or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")	DERWENT;	
17	-	0	or ("4954142") or ("5084071") or ("5225034") or ("5340370") or ("5478436") or ("5527423") or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")	US-PGPUB	2002/08/15 07:24
C((""3889753") or ("4090563") or ("4541945") or ("\$340370") or ("\$59804071") or ("\$527423") or ("\$540370") or ("\$57862780") or ("\$597423") or ("\$5978262") or ("\$597923") or ("\$5978262") or ("\$5979270") or ("\$5978260") or ("\$5981454") or ("\$5979270") or ("\$6478436") or ("\$5981454") or ("\$5981454") or ("\$6033993") or ("\$898260")).PN.) and (amine amide) and organic and pad and surface and clean "09/163368"  - 8 "163368" USPAT; US-PGPUB; EFO, JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO, JPO; DERWENT; IBM	-	17	(("3889753") or ("4090563") or ("4541945") or ("4954142") or ("5084071") or ("5225034") or ("5340370") or ("5478436") or ("5527423") or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454")	USPAT	2002/08/15 14:41
- 8 "163368"  - 8 "163368"  - 8 "163368"  - 8 "163368"  - 10 "09/163368"  - 10 "09/163368"  - 10 "09/163368"  - 10 "09/163368"  - 10 "163368"  - 11 "163368"  - 11 "163368"  - 12 ("5,981,454").PN.  - 12 ("5,981,454").PN.  - 13 "17 "18 "18 "18 "18 "18 "18 "18 "18 "18 "18			((("3889753") or ("4090563") or ("4541945") or ("4954142") or ("5084071") or ("5225034") or ("5340370") or ("5478436") or ("5527423") or ("5645682") or ("5662769") or ("5509970") or ("5876508") or ("5879226") or ("5981454") or ("6033993") or ("5830280")).PN.) and (amine amide) and organic and pad and	US-PGPUB; EPO; JPO; DERWENT;	2002/08/15 07:26
- 8 "163368" USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO	-	0		US-PGPUB; EPO; JPO; DERWENT;	2002/08/15 14:45
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	8	"163368"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/15 14:46
- ("6,280,299").PN.    SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	2	("5,981,454").PN.	US-PGPUB; EPO; JPO; DERWENT;	2003/07/14 16:06
cu and cmp and ph and polish and clean composition and organic and amine and wafer and complex  3131 cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex  8 cu and cmp and ph near2 ("8" "11") and polish and clean and complex  Cu and cmp and ph near2 ("8" "11") and polish and clean and composition and polish and clean and composition and polish and clean and composition and polish and clean and wafer and complex  8 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and polish and clean and composition and polish and clean and wafer and complex  8 polish\$3 near3 pad near10 clean\$3  Cu and cmp and ph near2 ("8" "11") and USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;	-	2	("6,280,299").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/16 06:45
cu and cmp and ph near2 ("8" "11") and polish and clean composition and organic and amine and wafer and complex  8 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and polish and clean and composition and polish and clean and wafer and complex  9 cu and cmp and ph near2 ("8" "11") and polish and clean and composition and polish and clean and wafer and complex  9 polish\$3 near3 pad near10 clean\$3  9 polish\$3 near3 pad near10 clean\$3  10 polish\$3 near3 pad near10 clean\$3  2003/07/16 06:48  2003/07/16 06:48  2003/07/16 06:48	-	3223	composition and organic and amine and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/16 06:47
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